

AN 1999-622788 [54] WPIDS  
DNN N1999-459554 DNC C1999-182239  
TI Solder for mounting precision components such as small- sized chips on circuit board - has lead as principal component with specified amounts of tin, antimony, copper, silver, phosphorus, germanium and nickel.  
DC L03 M23 M25 P55 V04  
PA (ISHI-N) ISHIKAWA KINZOKU KK  
CYC 1  
PI JP 11267880 A 19991005 (199954)\* 17<--  
ADT JP 11267880 A JP 1998-73710 19980323  
PRAI JP 1998-73710 19980323  
AB JP 11267880 A UPAB: 20000105  
NOVELTY - The solder contains chemical composition of **pb**, 60-65 weight% of **Sn**, 0.1-1 weight% of **Sb**, 0.01-0.1 weight% of **Cu**, 0.1-1 weight% of **Ag**, 0.001-0.01 weight% of **P**, 0.005-0.05 weight% of **Ge** and 0.001-0.01 weight% of **Ni**.  
USE - Solder is used for mounting precision small-sized chip components, semiconductor component on circuit board of electronic, electrical equipments.  
ADVANTAGE - The solder excels in heat resistance and creep- proof characteristic. When soft soldering of electronic machines is performed, the crack or peeling by the thermal fatigue does not occur.  
Dwg.1/2